DECLARATION FOR PATENT APPLICATION

Attorney Docket: 25618 Page 1 of 2

As a below-named inventor(s), I/we hereby declare that:

My/Our residence(s), post office address(es) and citizenship(s) is/are as stated below next to my/our name(s).

I/We believe I/we am/are the original inventor, first and sole (if only one name is listed below) or the original, first and joint inventors (if plural names are listed below) of the subject matter

which is claimed, and for whi the specification of which:	.ch a patent is sought on the BUFFER SYSTEM FOR A WAFER HAI (check one)			
[] is attached here	eto.			
[] was filed on	, as Serial No			
and was amended	and was amended on (if applicable).			
	we have reviewed and underst	tand the contents of the aborendment referred to above.	ve-identified	
We acknowledge the duty application as defined by 37		h is material to the patentab	ility of this	
patent or inventor's certific	ate listed below, and have als	S.C. § 119 of any foreign appliso identified below any foreige before that of the applica	n application	
Prior Foreign Applications:		Dri	ority Claimed	
128987 (Application No.)	IL (Country)	17 /Jan / 1999 (Day/Month/Year Filed)	[X] []	
(Application No.)	(Country)	(Day/Month/Year Filed)	[] [] Yes No	
(Application No.)	(Country)	(Day/Month/Year Filed)	[] [] Yes No	
We hereby appoint Gary M. Nath, Reg. No. 26,965; Harold L. Novick, Reg. No. 26,011; Todd L. Juneau, Reg. No. 40,669; Lee C. Heiman, Reg. No. 41,827; Jerald L. Meyer, Reg. No. 41,194; Joshua B. Goldberg, Reg. No. 44,126; Marvin C. Berkowitz, Reg. No. 47,421; Sheldon McGee, Reg. No. 50,454; Tanya E. Harkins, Reg. No. 52,993; and Robert C. Ryan, Reg. No. 29,343; as my attorneys to prosecute this application and transact all business in the U.S. Patent and Trademark Office connected therewith.				
Direct Telephone Calls to:		Send Correspondence to: NATH & ASSOCIATES PLLC Sixth Floor		
<u>Gary M. Nath</u> (202) 775-8383		1030 15 th Street, N.W. Washington, D.C. 20005 U.S.	A.	
and, insofar as the subject m prior United States applicat acknowledge the duty to disc	matter of each of the claims of ion in the manner provided b close material information as	y United States application(s) of this application is not dispoy 35 U.S.C. § 112, first pass defined in 37 CFR § 1.56 wational or PCT international f	closed in the ragraph, I/we hich occurred	
09/822.505	unknown	Pending		

09/822,505	<u>unknown</u>	<u> Pending</u>
(U.S. Application Serial No.)	(U.S. Filing Date)	(Statuspatented, pending, abandoned)
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09/248,070	Feb. 11, 1999	<u>Patented</u>
(U.S. Application Serial No.)	(U.S. Filing Date)	(Statuspatented, pending, abandoned)

DECLARATION FOR PATENT APPLICATION

Full name of fifth inventor:_____

Post Office Address: ______

Country of Citizenship:

Attorney Docket: 25618 Page 2 of 2

I/We hereby claim the benefit under 35 U.S.C 119(e) of any United States provisional application(s) listed below:

(Application Number(s) Filing Date We hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements are made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon. Full name of sole or first inventor: Eran DVIR Inventor's Signature ______ Date ______ Residence: 15 Hapalmach Street, Givatayim 53406 ISRAEL Country of Citizenship: <u>ISRAEL</u> Post Office Address: __same as above Full name of second inventor:______ Inventor's Signature _____ ______ Date _____ Residence:____ Country of Citizenship: Post Office Address: Full name of third inventor:______ Inventor's Signature _____ Date ____ Residence:_____ Country of Citizenship: Post Office Address: __same as residence Full name of fourth inventor: Inventor's Signature _____ Date _____ Residence:_____ Country of Citizenship: __ Post Office Address: _ same as residence _

Inventor's Signature ______ Date _____